Product / Process
Change Notification

N° 2019-153-A2

Dear Customer,

please find attached our INFINEON Technologies PCN:

Final PCN: Several changes affecting Gen4 IGBT for Super TO-220. TO247. D2Pak packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-03-10.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”

  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon Technologies to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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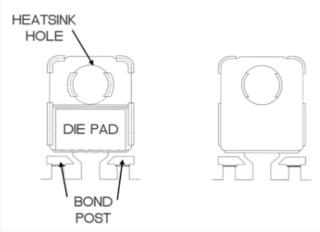
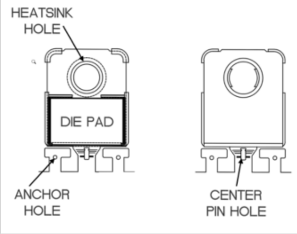
Products affected	Please refer to attached affected product list 1_cip19153_A2

Detailed Change Information

Subject:	Final PCN: Several changes affecting Gen4 IGBT for Super TO-220. TO247. D2Pak packages
Reason / Motivation:	Production Consolidation

Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip backside)	Cr / Ni / Ag	Al / Ti / Ni / Ag
PROCESS - WAFER PRODUCTION: New / change of metallization (specifically chip frontside)	Al /Si	Al / Si / Cu
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Infineon Technologies Americas Corp., Temecula, United States	EPISIL Technologies Inc.
PROCESS - ASSEMBLY: Change in leadframe dimensions	AUIRGDC0250: Single Gauge AUIRG4PH50S, AUIRG4PC40S-E- Mold locking features 	AUIRGDC0250: Dual Gauge ASEWH only AUIRG4PH50S, AUIRG4PC40S- Mold locking features 
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	AUIRGDC0250, AUIRG4BC30SSTRL: Ni plated in all area except die pad	AUIRGDC0250, AUIRG4BC30SSTRL: Bare Copper except Tpost
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	AUIRGDC0250 Only: KMC2110G-7S	AUIRGDC0250 Only: EME-G700HF

PROCESS - ASSEMBLY: Change of product marking	AUIRG4PH50S, AUIRG4PC40S-E Site Code: "A" AUIRGDC0250 Site Code: "P" AUIRG4BC30SSTRL Site Code: "A"	AUIRG4PH50S, AUIRG4PC40S-E Site Code: "D" AUIRGDC0250 Site Code: "J" AUIRG4BC30SSTRL Site Code: "M"
PROCESS - ASSEMBLY: Change of specified assembly process sequence (deletion and/or additional process step)	AUIRGDC0250: No 1x reflow	AUIRGDC0250: 1x reflow
PROCESS - ASSEMBLY: Move of all or part of assembly to a different location/site/subcontractor.	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and AUIRG4PH50S, AUIRG4PC40S-E : Great Team Backend Foundry,China AUIRGDC0250: ASE Weihai Inc. AUIRG4BC30SSTRL: Tongfu Microelectronics Co., Ltd
PACKING/SHIPPING: Change of carrier (tray, reel)	AUIRG4BC30SSTRL only: Reel 43-8364 Cover Tape 44-0196 Carrier Tape 44-0194	AUIRG4BC30SSTRL Only: Reel REL-X0009 Reel Cover Tape TFME Carrier Tape EMB-X0048
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	Wafer Probe site: Infineon Technologies Americas Corp., Temecula, United States Final Test site: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico	Wafer Probe site: EPISIL Technologies Inc. Final Test site Final Test site: Rectificadores Internacionales, S.A. de C.V., Tijuana , Mexico and TO247, TO247LL: Great Team Backend Foundry,China Final Test site STO220 : ASE Weihai Inc. Final Test site D2Pack: Tongfu Microelectronics Co., Ltd

Product Identification

Traceability assured via Lot number

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Anticipated Impact of Change	No expected impact on electrical performance. Quality and reliability verified by qualification. DeQuMa-ID(s): SEM-PW-06 / SEM-PW-07 / SEM-PW-13 / SEM-PA-03 / SEM-PA-04 / SEM-PA-11 / SEM-PA-13 / SEM-PA-17 / SEM-PA-18 / SEM-PS-03 / SEM-TF-01

Attachments

1_cip19153_A2	affected product list
3_cip19153_A2	customer information package

Time Schedule

Final qualification report	2021-01-15
First samples available	2021-01-15
Intended start of delivery [1]	2021-07-25
Last Order Date (LOD) [2]	2021-04-30
Last Delivery Date (LDD) [3]	2021-10-31

[1] provided date or earlier after customer approval
[2] Last time buy volume to be placed latest until LOD
[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local Sales Office.

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Sales name	SP number	OPN	Package
AUIRG4BC30SSTRL	SP001511460	AUIRG4BC30SSTRL	PG-TO263-3-901
AUIRG4PC40S-E	SP001511242	AUIRG4PC40S-E	PG-TO247-3-901
AUIRG4PH50S	SP001512028	AUIRG4PH50S	PG-TO247-3-901
AUIRGDC0250	SP001511678	AUIRGDC0250	PG-TO273-3-900